

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0023] as shown in the following replacement paragraph:

[0023] An optional vent(s) 16 is provided in the side of the package lid 10 to allow gases to escape during package assembly and assembly of the packaged IC to a printed circuit assembly, which is typically a solder-reflow type of process. In a particular embodiment, the vent 16 comprises a gap in the sloped wall 12. Alternatively, the sloped wall 12 is continuous around the perimeter of the package lid 10 and a vent hole is provided in the top 18 or side of the package lid 10. An optional rim 20 provides a vertical wall.

Please amend paragraph [0027] as shown in the following replacement paragraph:

[0027] Fig. 2A is a simplified partial cross section of the package lid 10' of Fig. 1C assembled to a package substrate 24 taken across the solid portion of section line A-A' of Fig. 2B, below. The entire cross section is not shown (i.e. the dashed portion of section line A-A' is not shown) to allow clear labeling of layered features on the right side of cross section. The package substrate 24 typically includes a printed circuit board material, such as one based on bismaleimide triazine ("BT") resin or other polymer. A semiconductor IC 26 is mechanically and electrically coupled to the package substrate 24, such as with a BGA attachment (not shown). An optional pedestal 28 is provided between the semiconductor IC 26 and the package lid 10' to facilitate thermal conduction between the semiconductor 26, where heat is generated, and the package lid 10', which is optionally coupled to a heat sink or heat dissipater (not shown). Alternatively, the pedestal 28 is omitted and thermal grease is used between the semiconductor IC 26 and the package lid 10'.

Please amend paragraph [0030] as shown in the following replacement paragraph:

[0030] Chip capacitors 36, 38 are frequently mounted on the package substrate 24 around the perimeter of the semiconductor IC 26. The space 35 around the chip capacitors 36, 38 is not filled with molding compound. The set-back from the edge of the package substrate 24 to the chip capacitors 36, 38 is typically about 2-3 mm in some embodiments. The sloped wall 34 and molding compound therefore fit within the set-back, leaving enough of an exposed perimeter portion 32 of the surface of the package substrate 24 for the molding compound to bond to. In a particular embodiment, about 2 mm to about 3 mm of the perimeter of the package substrate 24 was exposed in the areas with molding compound 30. In prior art package assemblies using molded metal lids, the perimeter of the molded lid attached to the package substrate is also about 2 mm to about 3 mm. However, this amount of contact area proved insufficient to reliably secure the heavy molded lid to the substrate with epoxy adhesive. Several types of commercially available epoxy adhesives were tried, none of which worked acceptably.